

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

Claims 1-21 (Cancelled).

Claim 22. (Original) An electroplating copper bath comprising dissolved cupric salt at a concentration of at least about 0.4 molar, up to about 0.5 molar concentration of an acid and having an acidic pH.

Claim 23. (Original) The bath of claim 22 being free of complexing agent.

Claim 24. (Original) The bath of claim 23 wherein the cupric salt concentration is at least about 0.8 molar.

25.(New) The bath of claim 22 wherein the concentration of the cupric salt is at least about 0.8 molar.

26. (New) The bath of claim 22 wherein the cupric salt comprises CuSO_4 .

27. (New) The bath of claim 22 wherein the concentration of the acid is about 0.1 to about 0.25 molar.

28. (New) The bath of claim 22 wherein the acid comprises sulfuric acid.

29. (New) The bath of claim 22 wherein the having a pH of up to about 5.

30. (New) The bath of claim 22 having a pH of about 1.

31. (New) The bath of claim 22 further containing at least one auxiliary additive selected from the group consisting of brightener, leveling agent, ductility enhancer and stress reducer.